

L-Band, GaN/SiC, RF Power Transistor

960 - 1220 MHz | 6000 W typ | 75% Efficiency typ | 19 dB Gain typ | 125 V | 32μ s Pulse Length, 4% Duty Cycle

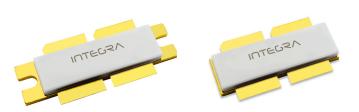
IGN0912S5000 and IGN0912S5000S are high power GaN-on-SiC RF power transistors that have been designed to suit the unique needs of IFF/SSR avionics systems. Under 32μ s, 4% duty cycle pulse conditions, they supply 5000 W of peak output power, with 18dB of associated gain and 70% efficiency. They operate from a 125 V supply voltage. For optimal thermal efficiency, the transistors are housed in a metal-based package with an epoxy-sealed ceramic lid.

FEATURES

- GaN on SiC HEMT Technology
- Output Power >5000 W
- Pre-matched Input Impedance
- High Efficiency up to 75% during the RF pulse
- 100% RF Tested
- RoHS and REACH Compliant

APPLICATIONS

TACAN and DME Systems



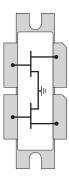


Table 1. RF Electrical Characteristics (Case temperature = 30 °C unless otherwise stated)

| Parameter | Symbol | Min | Тур | Max | Units | Test Conditions |
|-------------------------|----------|------|------|------|-------|--|
| Gain | G | 16 | 18 | 20 | dB | P _{out} = 5000W |
| Drain Efficiency | η | 60 | 70 | 80 | % | f = 960, 1090, 1220 MHz |
| Pulse Droop | D | -0.5 | -0.3 | +0.2 | dB | |
| Input Return Loss | IRL | 6 | 11 | 20 | dB | $32 \mu s$ pulse length, 4% duty cycle |
| Load Mismatch Stability | VSWR-S | 2:1 | | | | $V_{_{DS}} = 125V$, $I_{_{DS}} = 75mA$ per side |
| VSWR Withstand | VSWR-LMT | 3:1 | | | | |

Note 1: Consult Integra Technologies Application Note 001 for information on how RF output power and pulse droop are measured.

Table 2. DC Electrical Characteristics (Case temperature = 25 °C unless otherwise stated)

| Parameter | Symbol | Min | Тур | Max | Units | Test Conditions |
|------------------------|----------------|------|------|-----|-------|---|
| Gate Pinch-Off Voltage | V _P | -5.0 | | | V | $V_{_{\rm DS}}$ = 125V, $I_{_{\rm DS}}$ = 1mA |
| Quiescent Gate Voltage | V _q | | -2.8 | | V | $V_{_{\rm DS}}$ = 125V, $I_{_{\rm DS}}$ = 75mA per side |



Table 3. Absolute Maximum Ratings (Not Simultaneous)

| Parameter | Symbol | Value | Units | Test Conditions |
|-------------------------------|---------------------|-------------|-------|-----------------|
| DC Drain-Source Voltage | V _{DS} | 400 | V | 25 ºC |
| DC Gate-Source Voltage | V _{GS} | -8 to +1.0 | V | 25 ºC |
| DC Drain Current | I _D | 156 | А | 25 ºC |
| DC Gate Current | Ι _G | 156 | mA | 25 ºC |
| RF Input Power | P _{RF,IN} | 100 | W | 25 °C |
| Operating Channel Temperature | T, | -55 to +225 | ٥C | |
| Storage Temperature | T _{stg} | -55 to +150 | ٥C | |
| Soldering Temperature | T _{SOLDER} | 260 for 60s | ٥C | |

Note: Operation outside the limits given in this table may cause permanent damage to the transistor

Table 4. Thermal Resistance (Case temperature = 85 °C unless otherwise stated)

| Parameter | Symbol | Тур | Units | Test Conditions |
|---|-----------------|------|-------|---|
| Peak Thermal Resistance (total device), Channel to Case | R _{TH} | 0.04 | ⁰C/W | $\begin{array}{l} {\sf P}_{\rm diss}=2142W\\ 32\mu s \ {\rm pulse} \ {\rm length}, \ 4\% \ {\rm duty} \ {\rm cycle}\\ {\sf V}_{_{\rm DS}}=125V \end{array}$ |

Table 5. Test Fixture One Side to Ground Source & Load Impedances (Case temperature = 25 °C unless otherwise stated)

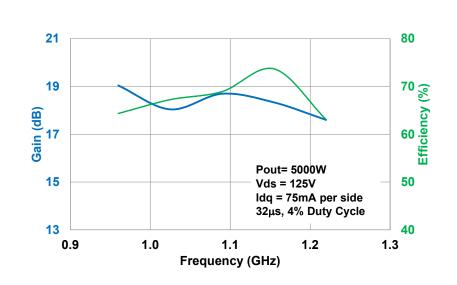
| Frequency (MHz) | ZIF | Z _{OF} | Units | Test Conditions |
|-----------------|---------------|-----------------|-------|--|
| 960 | 1.32 - j 1.48 | 2.18 - j 2.05 | Ω | |
| 1025 | 1.27 - j 0.88 | 2.21 - j 1.67 | Ω | P _{ουτ} = 5000W 32μs pulse length, 4% duty cycle |
| 1090 | 1.23 - j 0.30 | 2.23 - j 1.41 | Ω | $V_{DS} = 125V$, $I_{DS} = 75$ mA per side |
| 1155 | 1.24 + j 0.29 | 2.24 - j 1.22 | Ω | |
| 1220 | 1.26 + j 0.87 | 2.18 - j 1.10 | Ω | |

Note: Source and load impedances are single-sided port to a 125 Ohm load impedance and are measured looking into the test fixture.

IGN0912S5000 | RF Power Transistor IGN0912S5000S



TYPICAL PERFORMANCE

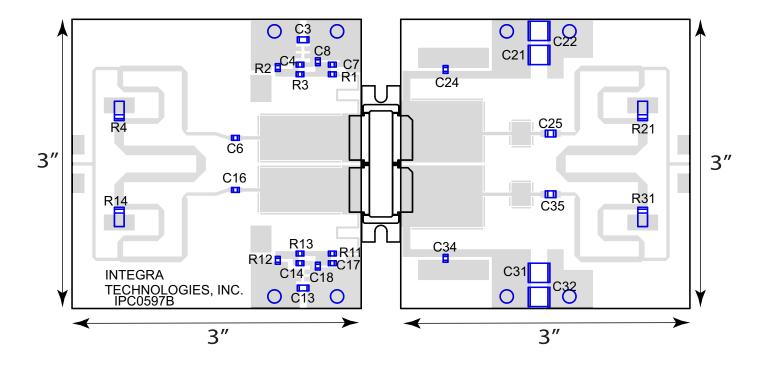


Gain & Efficiency vs Frequency

Figure 1



TEST FIXTURE

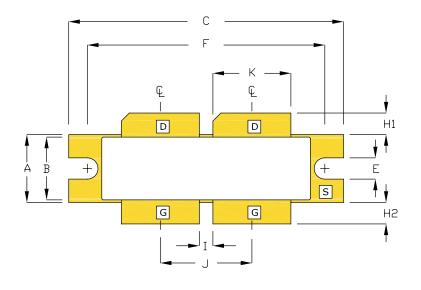


Bill of Materials for IGN0912S5000 Test Fixture

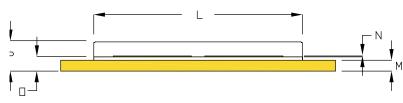
| Designator | Description | Quantity | Part Number |
|----------------------------|-------------------------------------|----------|---------------------|
| C3, C13 | CAP 1μF, 1206, 100V,X7R | 2 | 12061C105K4T2A |
| C4, C14 | CAP 0.068μF, 250V, 0805, X7R | 2 | C0805C683KARAC#A |
| C6, C7, C16, C17, C24, C34 | CAP 33pF, 0805 | 6 | ATC600F330 |
| C8, C18 | CAP 1000pF, 100v, 0805 | 2 | 08051A102J4T2A |
| C21, C22, C31, C32 | CAP 2.2μF, 250V, 2220, X7R | 4 | C5750X7T2E225K250KA |
| C25, C35 | CAP 150pF, 1111 | 2 | 800B151JT300XT |
| R1, R11 | RES 15 OHM, 0805 | 2 | CRCW080515R0JNEA |
| R2, R12 | RES 100 OHM, 0805 | 2 | CRCW0805100RFKTA |
| R3, R13 | RES 0 OHM, 0805 | 2 | CRCW08050000ZSTA |
| R4, R14, R21, R31 | RES 50 OHM, 120W, 2010 | 4 | NDC-2010SEW50R0G |
| PC Board Type | ROGERS RO3006, 25mil, 2/2oz. Copper | 2 | |



PACKAGE PL124A1

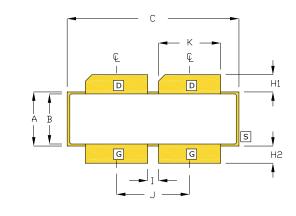


| | INCHES | 5 | MILLIM | IETERS |
|-----|--------|-------|--------|--------|
| DIM | MIN | МАХ | MIN | MAX |
| Α | 0.395 | 0.405 | 10.03 | 10.29 |
| В | 0,366 | 0.374 | 9,29 | 9,49 |
| С | 1.615 | 1.625 | 41.02 | 41,27 |
| E | 0,120 | 0,130 | 3.05 | 3.30 |
| F | 1.395 | 1.405 | 35.43 | 35.69 |
| H1 | 0.120 | 0.130 | 3.05 | 3.30 |
| H2 | 0.120 | 0.130 | 3.05 | 3.30 |
| Ι | 0.075 | 0.085 | 1,90 | 2.16 |
| J | 0.535 | 0.545 | 13.59 | 13.84 |
| К | 0,455 | 0,465 | 11.55 | 11.81 |
| L | 1.218 | 1.242 | 30.93 | 31.54 |
| М | 0.059 | 0.069 | 1,499 | 1.752 |
| N | 0.004 | 0.007 | 0.10 | 0.18 |
| | 0.079 | 0.089 | 2.00 | 2.26 |
| P | 0,165 | 0,188 | 4.19 | 4.77 |



| PIN : | SCHEDULE |
|-------|----------|
| D | DRAIN |
| S | SOURCE |
| G | GATE |

BOLT-DOWN FLANGE OPTION IGN0912S5000





| | INCHES | 2 | MILLIM | ETERS |
|-----|--------|-------|--------|-------|
| DIM | MIN | MAX | MIN | MAX |
| A | 0.395 | 0.405 | 10.03 | 10.29 |
| В | 0.366 | 0.374 | 9.29 | 9,49 |
| С | 1.265 | 1.275 | 32.13 | 32.38 |
| E | | | | |
| F | | | | |
| H1 | 0.120 | 0.130 | 3.05 | 3.30 |
| H2 | 0.120 | 0.130 | 3.05 | 3.30 |
| Ι | 0.075 | 0.085 | 1.90 | 2.16 |
| J | 0.535 | 0,545 | 13.59 | 13.84 |
| К | 0.455 | 0.465 | 11.55 | 11.81 |
| L | 1.218 | 1.242 | 30.93 | 31.54 |
| М | 0.059 | 0.069 | 1.499 | 1.752 |
| Ν | 0.004 | 0.007 | 0.10 | 0.18 |
| | 0.079 | 0.089 | 2.00 | 2.26 |
| Р | 0.165 | 0,188 | 4.19 | 4.77 |

| PIN | SCHEDULE |
|-----|----------|
| D | DRAIN |
| S | SOURCE |
| G | GATE |
| | |

EARLESS FLANGE OPTION IGN0912S5000S



ESD & MSL Rating

| Parameter | Rating | Standard |
|------------------------------------|----------------------|------------------------|
| ESD Human Body Model (HBM) | TBD | ESDA/JEDEC JS-001-2012 |
| ESD Charged Device Model (CDM) TBD | | JEDEC JESD22-C101F |
| Moisture Sensitivty Level (MSL) | Unlimited Shelf Life | IPC/JEDEC J-STD-020 |

RoHS Compliance

Integra Technologies, Inc declares that its GaN and LDMOS Transistor Products comply with EU Directive 2011/65/EU on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS2), as adopted by EU member states on January 2, 2013 and amended on March 31, 2015 by EU Directive 2015/863/EU.

REACH Compliance

Integra Technologies supports EU Regulation number 1907/2006 concerning the Registration, Evaluation, Authorization, and Restriction of Chemicals (REACH) as these apply to Integra semiconductor products, development tools, and shipping packaging.

In support of the REACH regulation, Integra will:

- Inform customers and recipients of Integra product if they contain any substances that are of very high concern (SVHC) per the European Chemical Agency (ECHA) website.
- •Notify ECHA if any Integra product that contains any SVHCs which exceed guidelines for REACH chemicals by weight per part number and for total content weight per year for all products produced in or imported to the European market.
- Cease shipments of product containing REACH Annex XIV substances until authorization has been obtained.
- -Cease shipment of product containing REACH Annex XVII chemicals when restrictions apply.

Integra has evaluated its materials, BOMs, and product specifications and product and has determined that this transistor conforms to all REACH and SVHC regulations and guidelines. Integra has implemented actions and control programs that will assure continued compliance.

Disclaimer

Integra Technologies Inc. reserves the right to make changes without further notice to any products herein. Integra Technologies Inc. makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Integra Technologies Inc. assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. Integra Technologies Inc. products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Integra Technologies Inc. customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Integra Technologies Inc. for any damages resulting from such improper use or sale.

DEFINITIONS:

DATA SHEET STATUS

Advanced Specification - This data sheet contains Advanced specifications.

Preliminary Specification - This data sheet contains specifications based on preliminary measurements and data.

Final Specification - This data sheet contains final product specifications.

Integra Technologies, 321 Coral Circle, El Segundo, CA 90245-4620 | Phone: 310-606-0855 | Fax: 310-606-0865

MAXIMUM RATINGS Stress above one or more of the maximum ratings may cause permanent damage to the device. These are maximum ratings only operation of the device at these or at any other conditions above those given in the characteristics sections of the specification is not implied. Exposure to maximum values for extended periods of time may affect device reliability.